

Product Summary

Device	BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
Q1	20V	0.99Ω @ V _{GS} = 4.5V	0.5A
		1.2Ω @ V _{GS} = 2.5V	0.45A
		1.8Ω @ V _{GS} = 1.8V	0.37A
		2.4Ω @ V _{GS} = 1.5V	0.32A
Q2	-20V	1.9Ω @ V _{GS} = -4.5V	-0.36A
		2.4Ω @ V _{GS} = -2.5V	-0.32A
		3.4Ω @ V _{GS} = -1.8V	-0.27A
		5.0Ω @ V _{GS} = -1.5V	-0.22A

Features

- Low On-Resistance
 - Very Low Gate Threshold Voltage
 - N-Channel: 1.0V Maximum
 - P-Channel: -1.0V Maximum
 - Low Input/Output Leakage
 - Fast Switching Speed
 - ESD Protected Gate
 - **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
 - **Halogen and Antimony Free. "Green" Device (Note 3)**
 - **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](https://www.diodes.com/quality/product-definitions/) or your local Diodes representative.**
- <https://www.diodes.com/quality/product-definitions/>

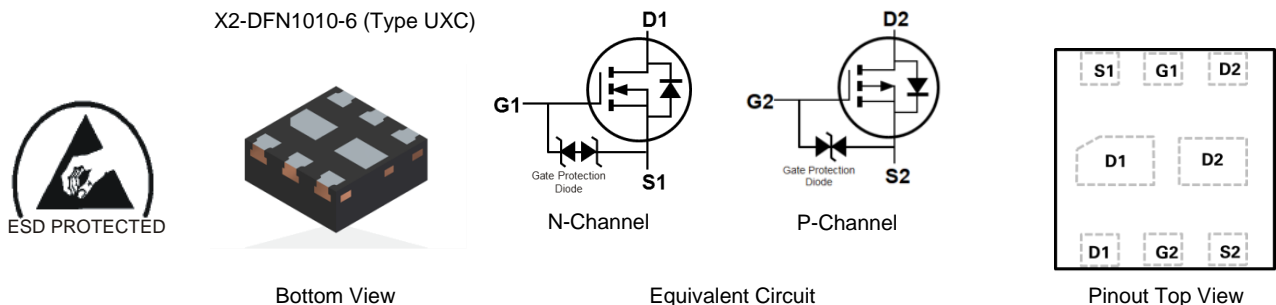
Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- Power-management functions
- Backlighting
- Load switches

Mechanical Data

- Package: X2-DFN1010-6
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 **(e4)**
- Weight: 0.0015 grams (Approximate)

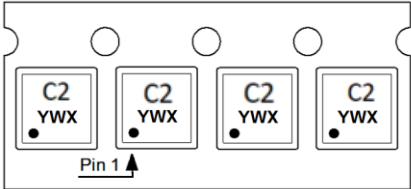


Ordering Information (Note 4)

Orderable Part Number	Package	Tape Width (mm)	Tape Pitch (mm)	Packing	
				Qty.	Carrier
DMC2991UDR4-7	X2-DFN1010-6 (Type UXC)	8	4	5000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

DMC2991UDR4-7	<div data-bbox="634 291 786 443"> <p>C2 YWX</p> </div> <div data-bbox="899 296 1474 420"> <p>C2 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 4 = 2024) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)</p> </div> <div data-bbox="496 466 904 653">  <p>Pin 1 ↑</p> </div>
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Date Code Key

Year	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	2	3	4	5	6	7	8	9	0	1	2	3
Week	1-26				27-52				53			
Code	A-Z				a-z				z			
Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat					
Code	T	U	V	W	X	Y	Z					

Maximum Ratings Q1 N-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	0.5 0.4	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	0.3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	1.4	A

Maximum Ratings Q2 P-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	-0.36 -0.3	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	-0.3	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	-0.8	A

Thermal Characteristics

Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 5)			P _D	0.37	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		R _{θJA}	337	°C/W
Total Power Dissipation (Note 6)			P _D	0.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State		R _{θJA}	178	°C/W
Operating and Storage Temperature Range			T _J , T _{STG}	-55 to +150	°C

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

Electrical Characteristics Q1 N-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	—	—	V	V _{GS} = 0V, I _D = 10μA
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	—	—	1	μA	V _{DS} = 16V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±10	μA	V _{GS} = ±5V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	0.4	—	1.0	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	0.5	0.99	Ω	V _{GS} = 4.5V, I _D = 100mA
		—	0.6	1.2		V _{GS} = 2.5V, I _D = 50mA
		—	0.7	1.8		V _{GS} = 1.8V, I _D = 20mA
		—	0.9	2.4		V _{GS} = 1.5V, I _D = 10mA
Diode Forward Voltage	V _{SD}	—	0.8	1.0	V	V _{GS} = 0V, I _S = 150mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	14.6	—	pF	V _{DS} = 16V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	4.7	—		
Reverse Transfer Capacitance	C _{rss}	—	3.2	—		
Total Gate Charge	Q _g	—	0.28	—	nC	V _{GS} = 4.5V, V _{DS} = 10V I _D = 250mA
Gate-Source Charge	Q _{gs}	—	0.04	—		
Gate-Drain Charge	Q _{gd}	—	0.1	—		
Turn-On Delay Time	t _{D(ON)}	—	7.1	—	ns	V _{DD} = 10V, V _{GS} = 4.5V R _L = 47Ω, R _G = 10Ω I _D = 200mA
Turn-On Rise Time	t _R	—	18	—		
Turn-Off Delay Time	t _{D(OFF)}	—	125	—		
Turn-Off Fall Time	t _F	—	56.9	—		

Electrical Characteristics Q2 P-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current @T _C = +25°C	I _{DSS}	—	—	-1	μA	V _{DS} = -16V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±10	μA	V _{GS} = ±5V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	—	-1.0	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	1.7	1.9	Ω	V _{GS} = -4.5V, I _D = -100mA
		—	2.2	2.4		V _{GS} = -2.5V, I _D = -50mA
		—	2.9	3.4		V _{GS} = -1.8V, I _D = -20mA
		—	3.7	5.0		V _{GS} = -1.5V, I _D = -10mA
		—	—	—		V _{GS} = -1.5V, I _D = -10mA
Diode Forward Voltage	V _{SD}	—	-0.7	-1.1	V	V _{GS} = 0V, I _S = -10mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	17	—	pF	V _{DS} = -16V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	4.1	—		
Reverse Transfer Capacitance	C _{rss}	—	2.7	—		
Total Gate Charge	Q _g	—	0.3	—	nC	V _{GS} = -4.5V, V _{DS} = -10V I _D = -250mA
Gate-Source Charge	Q _{gs}	—	0.04	—		
Gate-Drain Charge	Q _{gd}	—	0.1	—		
Turn-On Delay Time	t _{D(ON)}	—	7.3	—	ns	V _{DD} = -15V, V _{GS} = -4.5V R _G = 2Ω, I _D = -200mA
Turn-On Rise Time	t _R	—	20.7	—		
Turn-Off Delay Time	t _{D(OFF)}	—	185	—		
Turn-Off Fall Time	t _F	—	97	—		

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.

Q1 N-CHANNEL

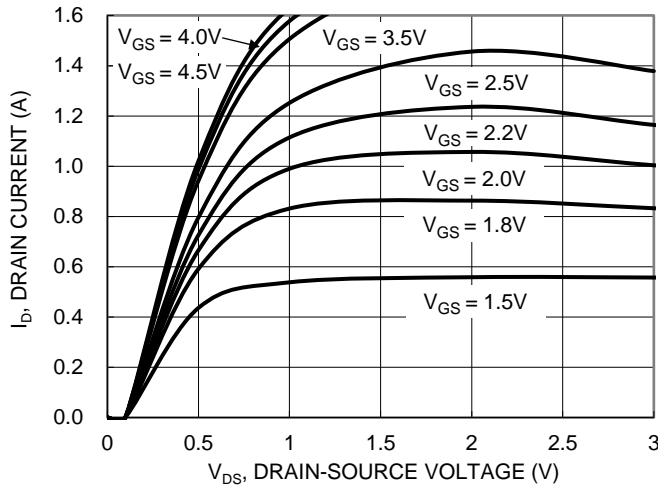


Figure 1. Typical Output Characteristic

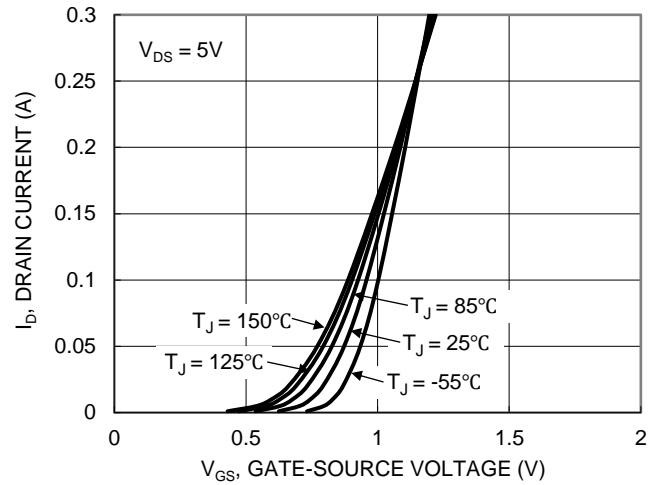


Figure 2. Typical Transfer Characteristic

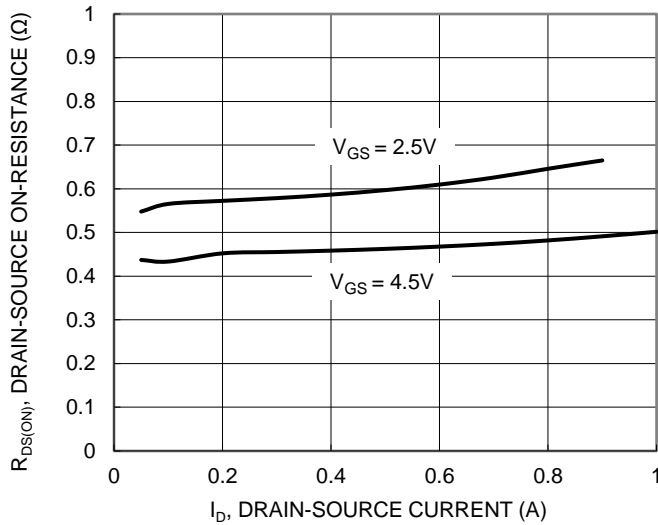


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

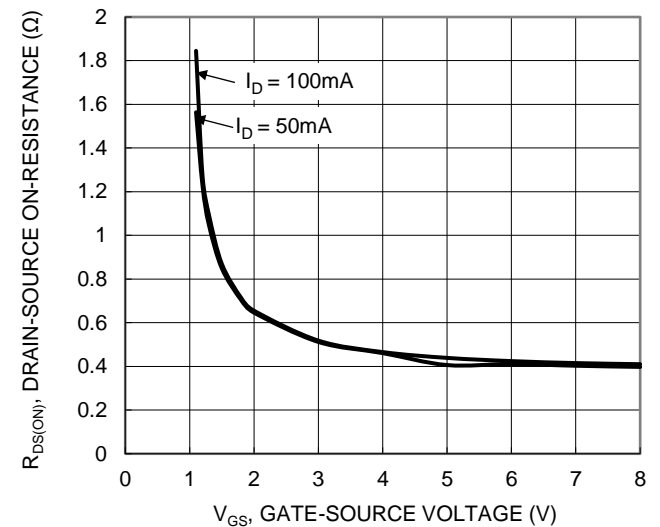


Figure 4. Typical Transfer Characteristic

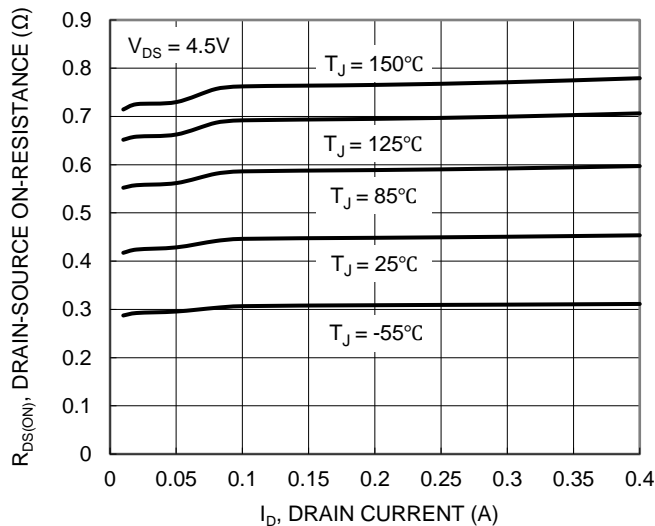


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

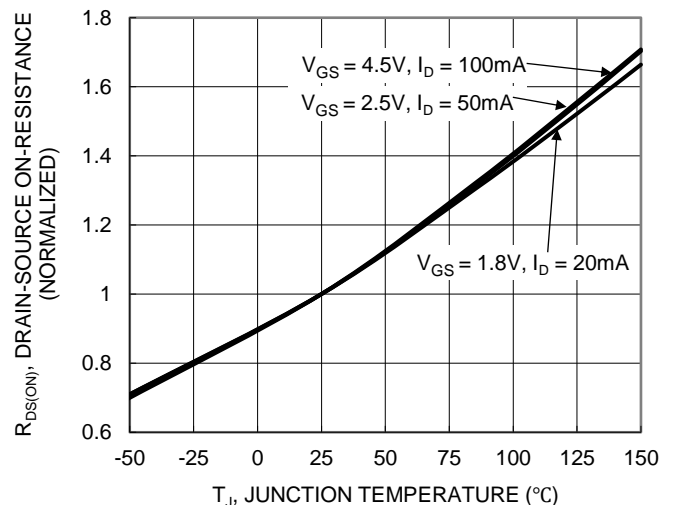
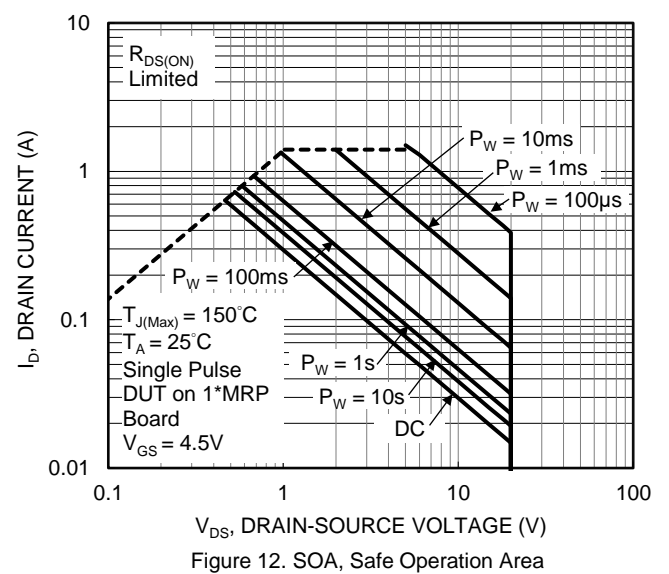
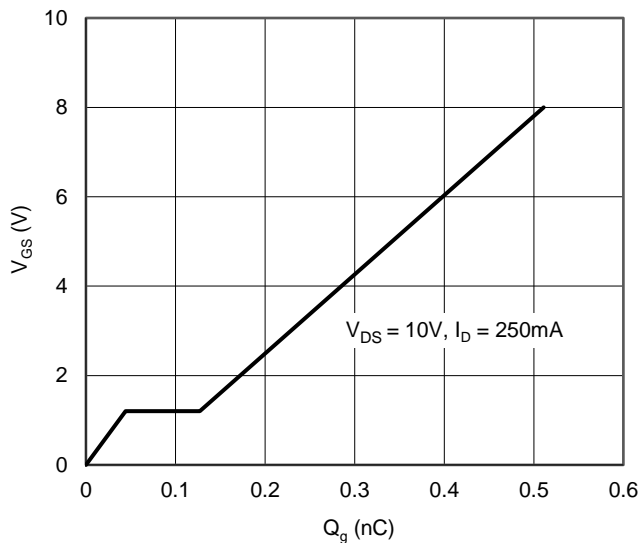
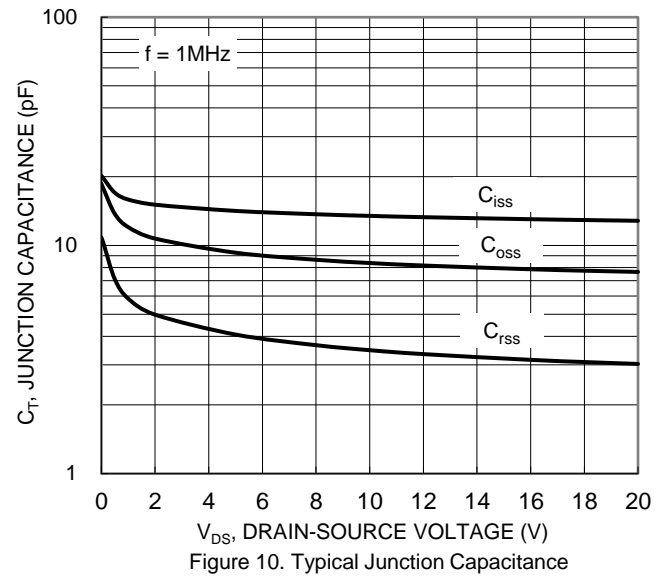
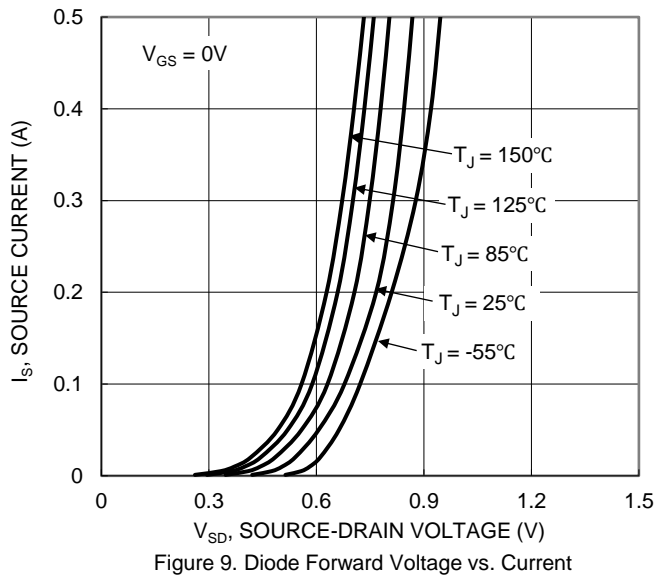
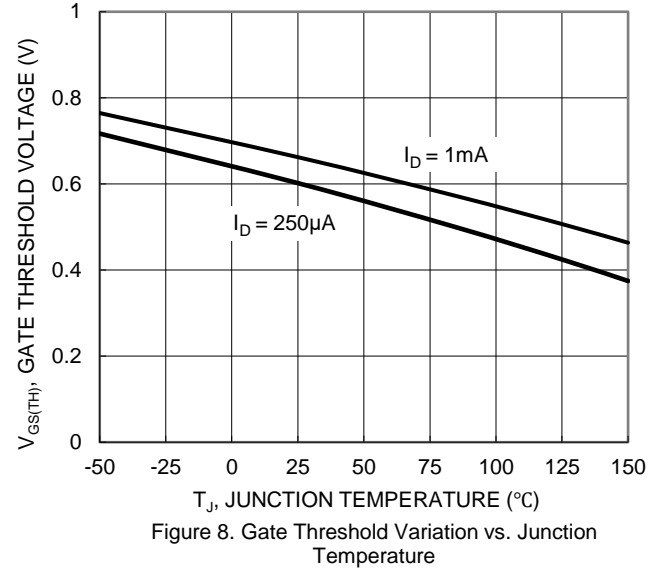
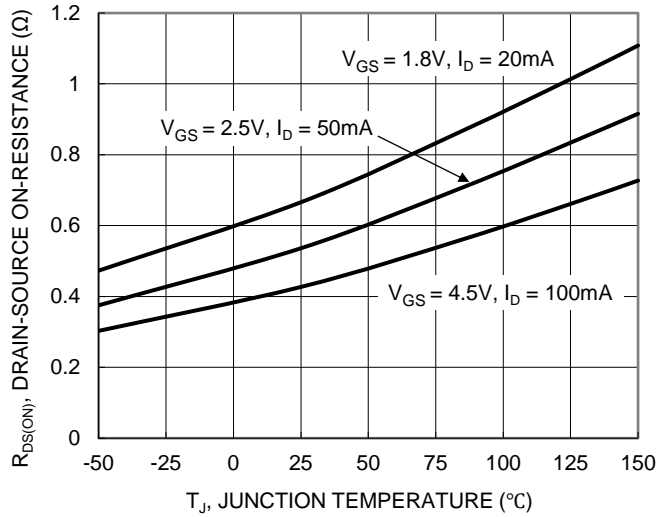


Figure 6. On-Resistance Variation with Junction Temperature



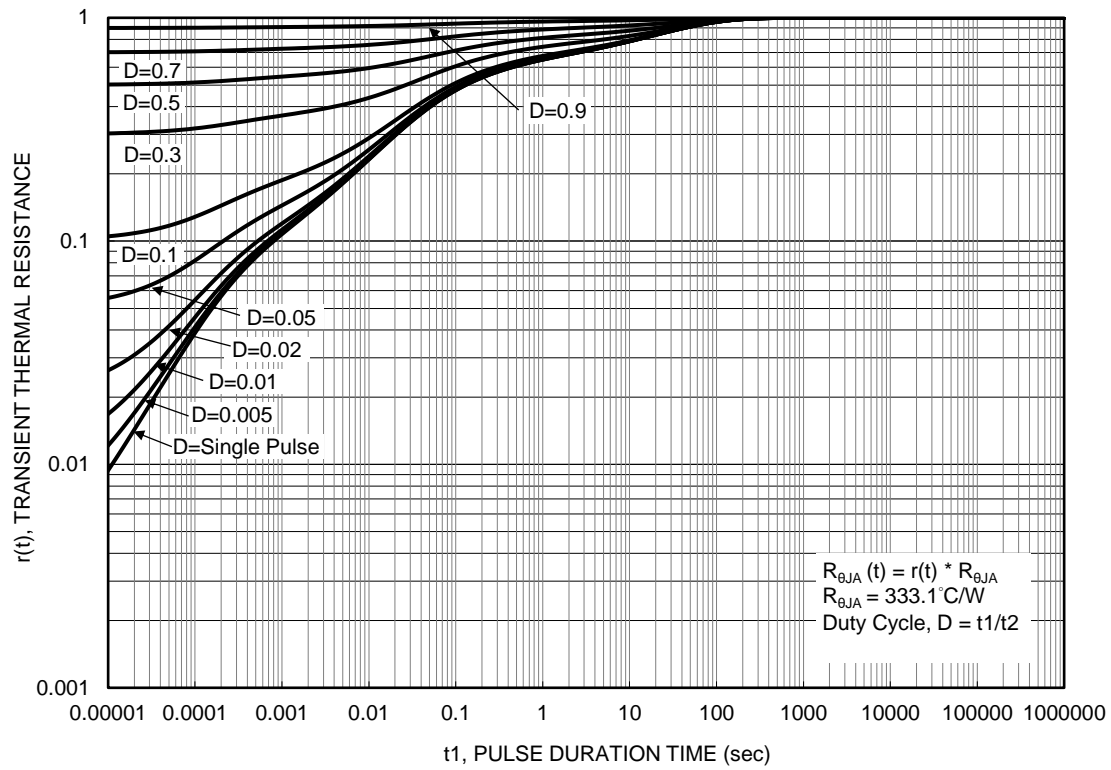


Figure 13. Transient Thermal Resistance

Q2 P-CHANNEL

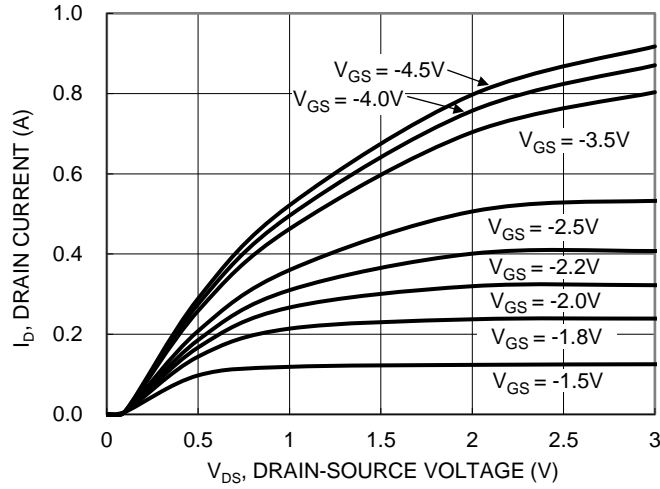


Figure 14. Typical Output Characteristic

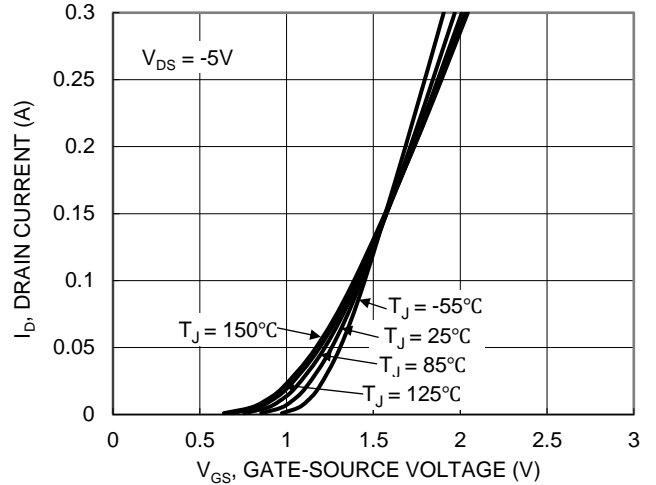


Figure 15. Typical Transfer Characteristic

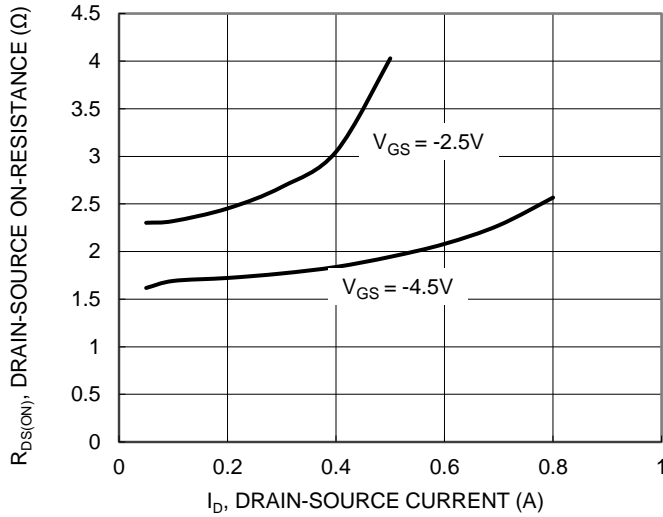


Figure 16. Typical On-Resistance vs. Drain Current and Gate Voltage

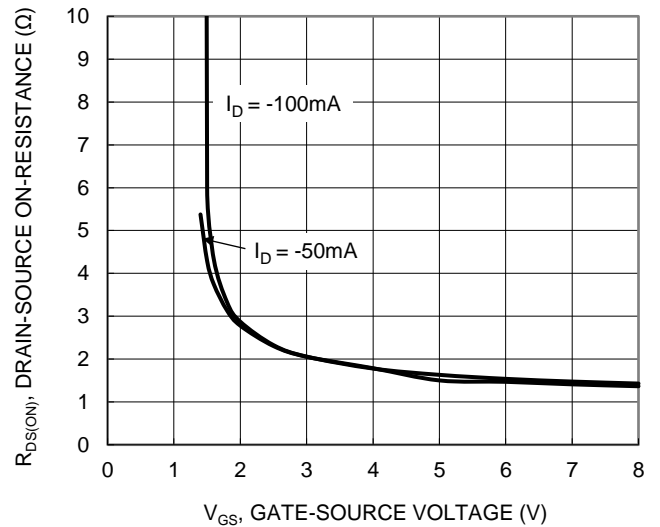


Figure 17. Typical Transfer Characteristic

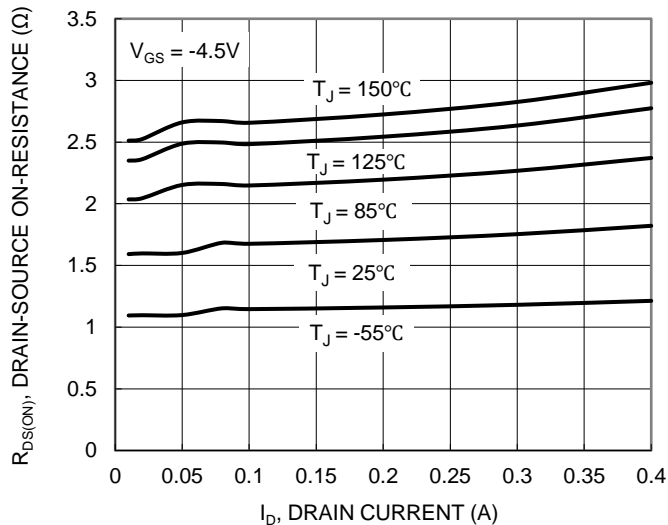


Figure 18. Typical On-Resistance vs. Drain Current and Junction Temperature

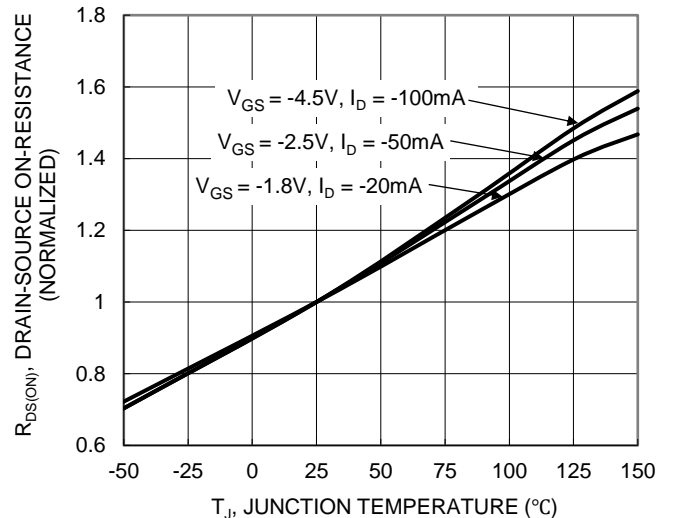
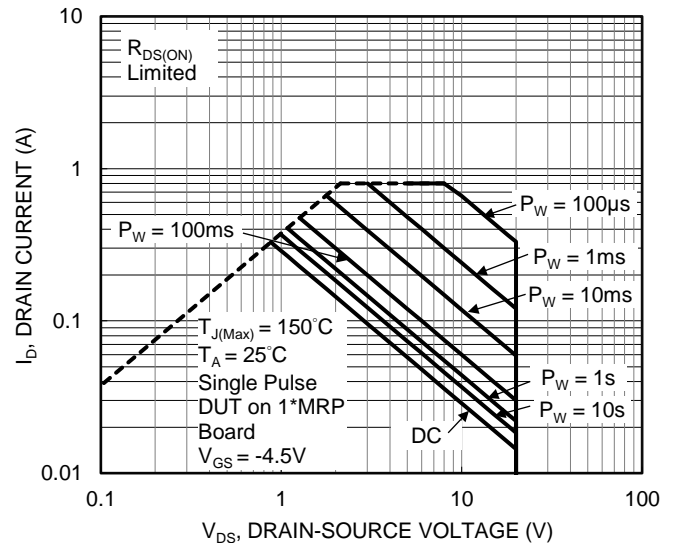
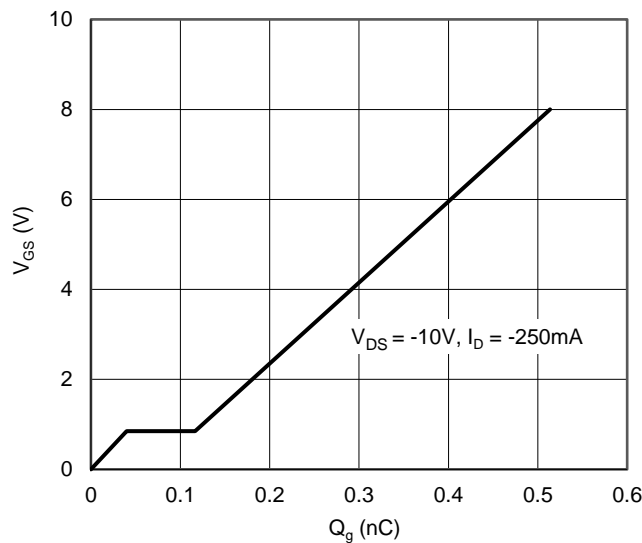
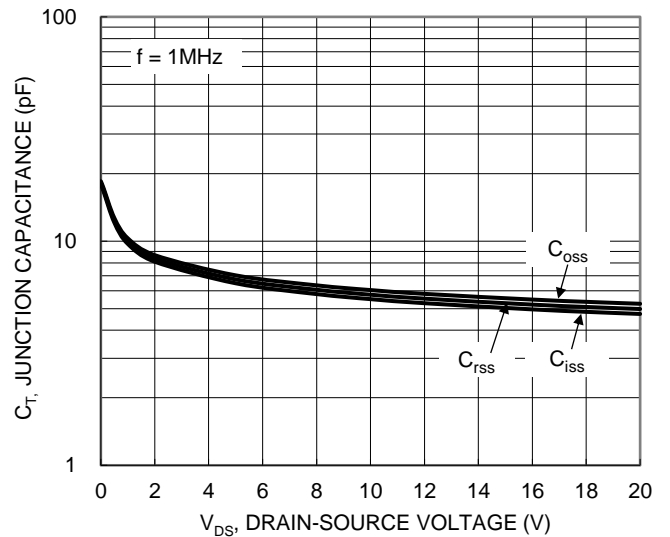
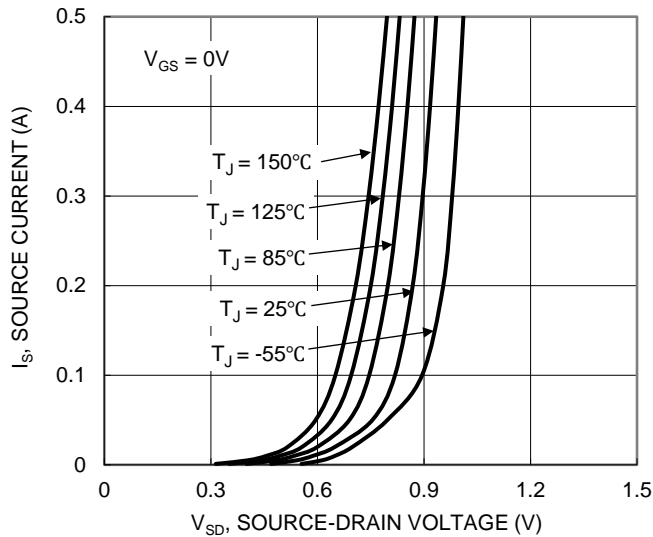
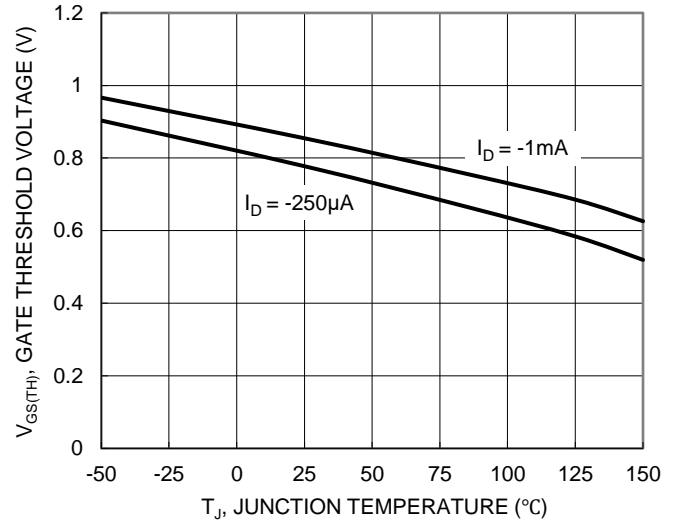
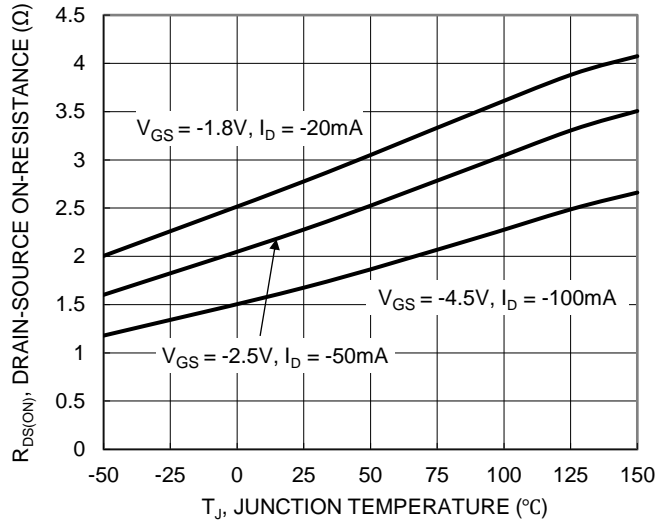


Figure 19. On-Resistance Variation with Junction Temperature



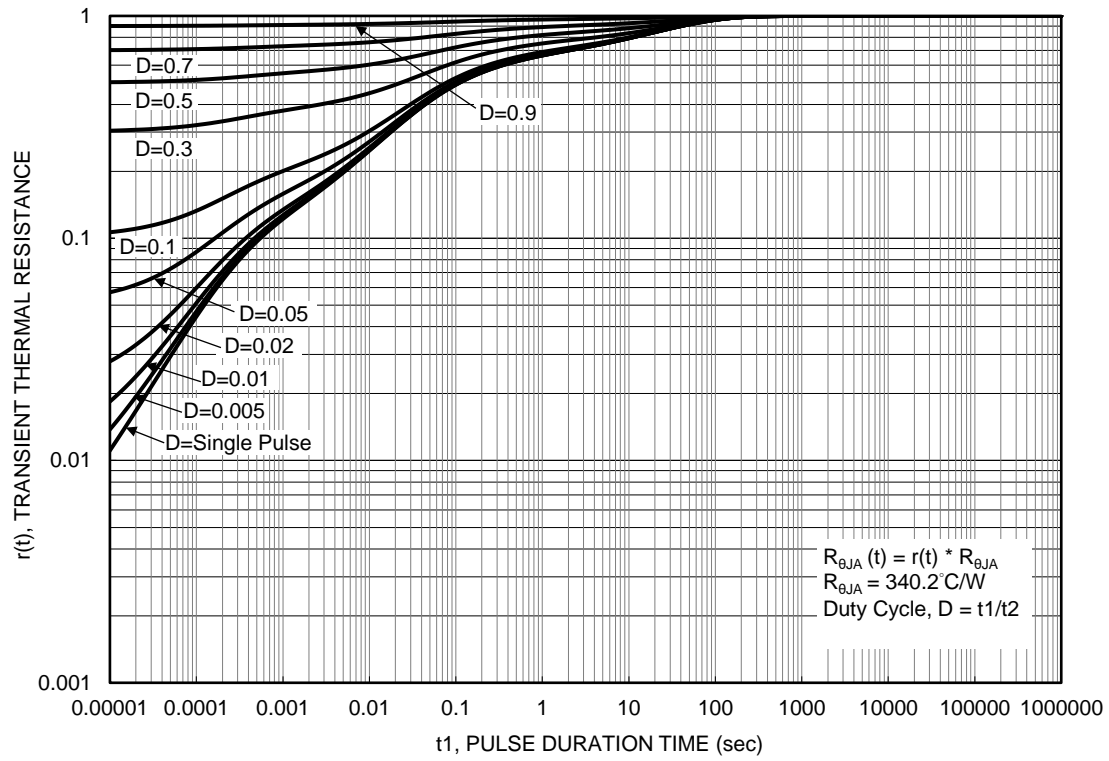
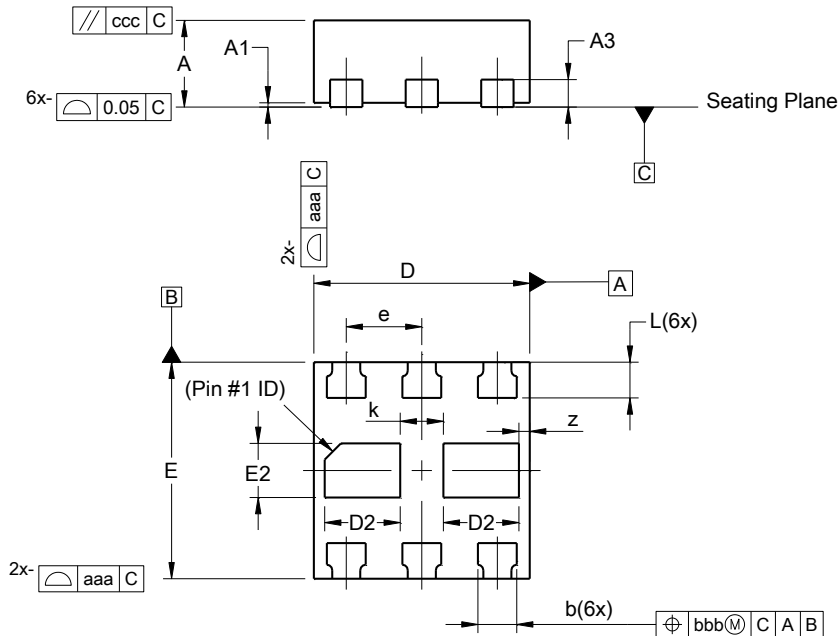


Figure 26. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6 (Type UXC)

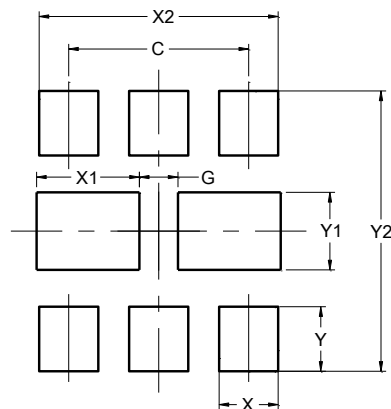


X2-DFN1010-6 (Type UXC)			
Dim	Min	Max	Typ
A	--	0.40	0.39
A1	--	0.05	--
A3	--	--	0.127
b	0.13	0.23	0.18
D	0.95	1.05	1.00
D2	0.30	0.40	0.35
E	0.95	1.05	1.00
E2	0.20	0.30	0.25
e	0.350 BSC		
L	0.115	0.215	0.165
k	--	--	0.20
z	0.02	0.08	0.05
aaa	0.08		
bbb	0.07		
ccc	0.05		
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN1010-6 (Type UXC)



Dimensions	Value (in mm)
C	0.700
G	0.300
X	0.230
X1	0.450
X2	0.930
Y	0.250
Y1	0.300
Y2	1.085

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